

# **Global Direct-to-chip Liquid Cooling Market Size study, by Cooling Solution Type, Component Cooling, Liquid Coolant Type, Application, End Use, and Regional Forecasts 2022-2032**

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## **Abstracts**

Global Direct-to-chip Liquid Cooling Market is valued at approximately USD 1.5 billion in 2023 and is anticipated to grow with an impressive compound annual growth rate of more than 20.5% over the forecast period 2024-2032. As data centers evolve to meet the escalating demands of high-performance computing, artificial intelligence, and cloud infrastructure, thermal management has emerged as a defining priority. Direct-to-chip liquid cooling, a disruptive approach that transfers heat directly from critical components to a circulating liquid medium, is gaining rapid traction due to its unmatched efficiency and energy-saving potential. By channeling coolants directly to heat-generating CPUs, GPUs, and memory modules, this method drastically reduces the need for air-cooling infrastructure and enhances system density—ushering in a new era of thermal innovation for next-generation computing environments.

A growing sense of urgency among hyperscale data centers, colocation providers, and enterprise IT environments to minimize power usage effectiveness (PUE) and carbon emissions is catalyzing adoption. Traditional air-based cooling systems are no longer sufficient to handle the heat generated by AI-intensive workloads and densely packed servers. Direct-to-chip solutions fill this gap by facilitating precise, localized cooling, while simultaneously enabling greater compute per rack. As global environmental regulations tighten and ESG pressures rise, enterprises are shifting their strategies toward sustainable infrastructure—thereby elevating liquid cooling technologies from experimental to essential.

The market is being further propelled by technological advancements in dielectric fluids

and thermal interface materials, which are broadening the application scope of direct-to-chip cooling. In particular, integration of smart sensors and closed-loop control systems allows real-time temperature optimization and predictive maintenance, reducing operational risk and prolonging hardware lifecycle. However, the transition from air to liquid requires overcoming legacy infrastructure barriers and necessitates upfront capital investment, system redesign, and technician retraining—factors that may impede early adoption in cost-sensitive segments. Nevertheless, growing R&D funding and strategic alliances among key players continue to bridge these gaps.

Strategic investments by semiconductor leaders, system integrators, and OEMs have significantly intensified competition, spurring rapid innovations in both single-phase and two-phase liquid cooling systems. As organizations race to optimize performance per watt and footprint utilization, modular and retrofit-friendly cooling systems are being aggressively deployed across new builds and legacy data centers alike. Additionally, the rise of edge computing and micro data centers in remote and space-constrained environments is creating untapped opportunities for compact and high-efficiency cooling technologies that ensure thermal stability without expanding energy budgets.

From a regional standpoint, North America currently leads the global direct-to-chip liquid cooling market, driven by early adoption among hyperscale data centers, favorable energy regulations, and advanced IT infrastructure. Europe follows closely, with strong policy support for green data center initiatives and increasing investments in digital transformation. Meanwhile, the Asia Pacific region is expected to exhibit the fastest growth throughout the forecast period. Rapid digitization in countries such as China, India, and Japan—coupled with the proliferation of cloud service providers and AI startups—has generated a surging demand for thermally efficient and scalable cooling systems tailored for high-density workloads.

**Major market player included in this report are:**

Vertiv Group Corp.

Schneider Electric SE

Asetek A/S

CoolIT Systems Inc.

Fujitsu Limited

Midas Green Technologies

Submer Technologies

Rittal GmbH & Co. KG

Chillydyne Inc.

Lenovo Group Limited

IBM Corporation

Advanced Cooling Technologies Inc.

Hewlett Packard Enterprise

Alibaba Group (via Alibaba Cloud)

LiquidStack

**The detailed segments and sub-segment of the market are explained below:**

By Cooling Solution Type

Single-Phase Cooling

Two-Phase Cooling

By Component Cooling

Processor Cooling (CPU, GPU)

Memory & Storage Cooling

Power Supply Unit (PSU)

Others

## By Liquid Coolant Type

Water-Based Coolants

Dielectric Fluids

Others

## By Application

High-Performance Computing (HPC)

Artificial Intelligence & Machine Learning

Edge Computing

Cloud Computing

Others

## By End Use

Data Centers

Enterprises

Government & Defense

Research & Academia

Others

## By Region:

## North America

U.S.

Canada

## Europe

UK

Germany

France

Spain

Italy

Rest of Europe

## Asia Pacific

China

India

Japan

Australia

South Korea

Rest of Asia Pacific

## Latin America

Brazil

Mexico

Middle East & Africa

Saudi Arabia

South Africa

Rest of Middle East & Africa

**Years considered for the study are as follows:**

Historical year – 2022

Base year – 2023

Forecast period – 2024 to 2032

**Key Takeaways:**

Market Estimates & Forecast for 10 years from 2022 to 2032.

Annualized revenues and regional level analysis for each market segment.

Detailed analysis of geographical landscape with Country level analysis of major regions.

Competitive landscape with information on major players in the market.

Analysis of key business strategies and recommendations on future market approach.

Analysis of competitive structure of the market.

Demand side and supply side analysis of the market.

#### Companies Mentioned

Vertiv Group Corp.

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Midas Green Technologies

Submer Technologies

Rittal GmbH & Co. KG

Childdyne Inc.

Lenovo Group Limited

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Hewlett Packard Enterprise

Alibaba Group (via Alibaba Cloud)

LiquidStack

## Contents

### **CHAPTER 1. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET EXECUTIVE SUMMARY**

- 1.1. Global Direct-to-chip Liquid Cooling Market Size & Forecast (2022-2032)
- 1.2. Regional Summary
- 1.3. Segmental Summary
  - 1.3.1. By Cooling Solution Type
  - 1.3.2. By Component Cooling
  - 1.3.3. By Liquid Coolant Type
  - 1.3.4. By Application
  - 1.3.5. By End Use
- 1.4. Key Trends
- 1.5. Recession Impact
- 1.6. Analyst Recommendation & Conclusion

### **CHAPTER 2. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET DEFINITION AND RESEARCH ASSUMPTIONS**

- 2.1. Research Objective
- 2.2. Market Definition
- 2.3. Research Assumptions
  - 2.3.1. Inclusion & Exclusion
  - 2.3.2. Limitations
  - 2.3.3. Supply Side Analysis
    - 2.3.3.1. Availability
    - 2.3.3.2. Infrastructure
    - 2.3.3.3. Regulatory Environment
    - 2.3.3.4. Market Competition
    - 2.3.3.5. Economic Viability (Provider's Perspective)
  - 2.3.4. Demand Side Analysis
    - 2.3.4.1. Energy Efficiency Mandates
    - 2.3.4.2. Technological Advancements in Coolants
    - 2.3.4.3. Sustainability & ESG Considerations
    - 2.3.4.4. Customer Awareness & Adoption
- 2.4. Estimation Methodology
- 2.5. Years Considered for the Study
- 2.6. Currency Conversion Rates



## **CHAPTER 3. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET DYNAMICS**

### **3.1. Market Drivers**

- 3.1.1. Escalating Heat Dissipation Requirements in Hyperscale Data Centers
- 3.1.2. Stringent Energy Efficiency and Carbon Reduction Targets
- 3.1.3. Proliferation of AI/ML Workloads Demanding High Compute Density

### **3.2. Market Challenges**

- 3.2.1. High Initial CapEx and Retrofit Complexity
- 3.2.2. Integration Barriers with Legacy Air-cooled Infrastructure
- 3.2.3. Limited Skilled Workforce for Liquid Cooling Deployment

### **3.3. Market Opportunities**

- 3.3.1. Emerging Edge Data Centers and Micro-server Deployments
- 3.3.2. Advances in Dielectric Fluids and Two-phase Cooling Technologies
- 3.3.3. Strategic Partnerships between OEMs and Coolant Suppliers

## **CHAPTER 4. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET INDUSTRY ANALYSIS**

### **4.1. Porter's 5 Force Model**

- 4.1.1. Bargaining Power of Suppliers
- 4.1.2. Bargaining Power of Buyers
- 4.1.3. Threat of New Entrants
- 4.1.4. Threat of Substitutes
- 4.1.5. Competitive Rivalry
- 4.1.6. Futuristic Approach to Porter's Model
- 4.1.7. Porter's 5 Force Impact Analysis

### **4.2. PESTEL Analysis**

- 4.2.1. Political
- 4.2.2. Economic
- 4.2.3. Social
- 4.2.4. Technological
- 4.2.5. Environmental
- 4.2.6. Legal

### **4.3. Top Investment Opportunities**

### **4.4. Top Winning Strategies**

### **4.5. Disruptive Trends**

### **4.6. Industry Expert Perspective**

### **4.7. Analyst Recommendation & Conclusion**

## **CHAPTER 5. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY COOLING SOLUTION TYPE (2022-2032)**

### 5.1. Segment Dashboard

### 5.2. Global Market: Cooling Solution Type Revenue Trend Analysis, 2022 & 2032 (USD Billion)

#### 5.2.1. Single-Phase Cooling

#### 5.2.2. Two-Phase Cooling

## **CHAPTER 6. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY COMPONENT COOLING (2022-2032)**

### 6.1. Segment Dashboard

### 6.2. Global Market: Component Cooling Revenue Trend Analysis, 2022 & 2032 (USD Billion)

#### 6.2.1. Processor Cooling (CPU, GPU)

#### 6.2.2. Memory & Storage Cooling

#### 6.2.3. Power Supply Unit (PSU) Cooling

#### 6.2.4. Others

## **CHAPTER 7. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY LIQUID COOLANT TYPE (2022-2032)**

### 7.1. Segment Dashboard

### 7.2. Global Market: Liquid Coolant Type Revenue Trend Analysis, 2022 & 2032 (USD Billion)

#### 7.2.1. Water-Based Coolants

#### 7.2.2. Dielectric Fluids

#### 7.2.3. Others

## **CHAPTER 8. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY APPLICATION (2022-2032)**

### 8.1. Segment Dashboard

### 8.2. Global Market: Application Revenue Trend Analysis, 2022 & 2032 (USD Billion)

#### 8.2.1. High-Performance Computing (HPC)

#### 8.2.2. Artificial Intelligence & Machine Learning

#### 8.2.3. Edge Computing

8.2.4. Cloud Computing

8.2.5. Others

## **CHAPTER 9. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY END USE (2022-2032)**

9.1. Segment Dashboard

9.2. Global Market: End Use Revenue Trend Analysis, 2022 & 2032 (USD Billion)

9.2.1. Data Centers

9.2.2. Enterprises

9.2.3. Government & Defense

9.2.4. Research & Academia

9.2.5. Others

## **CHAPTER 10. GLOBAL DIRECT-TO-CHIP LIQUID COOLING MARKET SIZE & FORECASTS BY REGION (2022-2032)**

10.1. North America Market

10.1.1. U.S. Market

10.1.1.1. Cooling Solution Type breakdown, 2022-2032

10.1.1.2. Component Cooling breakdown, 2022-2032

10.1.2. Canada Market

10.2. Europe Market

10.2.1. UK Market

10.2.2. Germany Market

10.2.3. France Market

10.2.4. Spain Market

10.2.5. Italy Market

10.2.6. Rest of Europe Market

10.3. Asia Pacific Market

10.3.1. China Market

10.3.2. India Market

10.3.3. Japan Market

10.3.4. Australia Market

10.3.5. South Korea Market

10.3.6. Rest of Asia Pacific Market

10.4. Latin America Market

10.4.1. Brazil Market

10.4.2. Mexico Market

- 10.4.3. Rest of Latin America Market
- 10.5. Middle East & Africa Market
  - 10.5.1. Saudi Arabia Market
  - 10.5.2. South Africa Market
  - 10.5.3. Rest of Middle East & Africa Market

## **CHAPTER 11. COMPETITIVE INTELLIGENCE**

- 11.1. Key Company SWOT Analysis
  - 11.1.1. Vertiv Group Corp.
  - 11.1.2. Schneider Electric SE
  - 11.1.3. Asetek A/S
- 11.2. Top Market Strategies
- 11.3. Company Profiles
  - 11.3.1. Vertiv Group Corp.
    - 11.3.1.1. Key Information
    - 11.3.1.2. Overview
    - 11.3.1.3. Financial (Subject to Data Availability)
    - 11.3.1.4. Product Summary
    - 11.3.1.5. Market Strategies
  - 11.3.2. Schneider Electric SE
  - 11.3.3. Asetek A/S
  - 11.3.4. CoolIT Systems Inc.
  - 11.3.5. Fujitsu Limited
  - 11.3.6. Midas Green Technologies
  - 11.3.7. Submer Technologies
  - 11.3.8. Rittal GmbH & Co. KG

## **CHAPTER 12. RESEARCH PROCESS**

- 12.1. Research Process
  - 12.1.1. Data Mining
  - 12.1.2. Analysis
  - 12.1.3. Market Estimation
  - 12.1.4. Validation
  - 12.1.5. Publishing
- 12.2. Research Attributes

## List Of Tables

### LIST OF TABLES

- TABLE 1. Global Direct-to-chip Liquid Cooling market, report scope
- TABLE 2. Global market estimates & forecasts by Region 2022-2032 (USD Billion)
- TABLE 3. Global market estimates & forecasts by Cooling Solution Type 2022-2032 (USD Billion)
- TABLE 4. Global market estimates & forecasts by Component Cooling 2022-2032 (USD Billion)
- TABLE 5. Global market estimates & forecasts by Liquid Coolant Type 2022-2032 (USD Billion)
- TABLE 6. Global market estimates & forecasts by Application 2022-2032 (USD Billion)
- TABLE 7. Global market estimates & forecasts by End Use 2022-2032 (USD Billion)
- TABLE 8. Global market by segment, estimates & forecasts, 2022-2032 (USD Billion)
- TABLE 9. North America market estimates & forecasts, 2022-2032 (USD Billion)
- TABLE 10. U.S. market estimates & forecasts by segment, 2022-2032 (USD Billion)
- TABLE 11. Canada market estimates & forecasts by segment, 2022-2032 (USD Billion)
- TABLE 12. Europe market estimates & forecasts by country, 2022-2032 (USD Billion)
- TABLE 13. Asia Pacific market estimates & forecasts by country, 2022-2032 (USD Billion)
- TABLE 14. Latin America market estimates & forecasts by country, 2022-2032 (USD Billion)
- TABLE 15. Middle East & Africa market estimates & forecasts by country, 2022-2032 (USD Billion)
- TABLE 16. Global market by company, market share analysis, 2023 (%)
- TABLE 17. Global market historical data comparison, 2022 vs 2023 (USD Billion)
- TABLE 18. Global market PUE improvement metrics by region
- TABLE 19. Global market energy consumption benchmarks
- TABLE 20. Global market investment & funding analysis, 2022-2023

## List Of Figures

### LIST OF FIGURES

- FIG 1. Global market, research methodology
- FIG 2. Global market, market estimation techniques
- FIG 3. Global market size estimates & forecast methods
- FIG 4. Global market, key trends 2023
- FIG 5. Global market, growth prospects 2022-2032
- FIG 6. Global market, Porter's 5 Force Model
- FIG 7. Global market, PESTEL analysis
- FIG 8. Global market, value chain analysis
- FIG 9. Global market by Cooling Solution Type, 2022 & 2032 (USD Billion)
- FIG 10. Global market by Component Cooling, 2022 & 2032 (USD Billion)
- FIG 11. Global market by Liquid Coolant Type, 2022 & 2032 (USD Billion)
- FIG 12. Global market by Application, 2022 & 2032 (USD Billion)
- FIG 13. Global market by End Use, 2022 & 2032 (USD Billion)
- FIG 14. Global market, regional snapshot 2022 & 2032
- FIG 15. North America market 2022 & 2032 (USD Billion)
- FIG 16. Europe market 2022 & 2032 (USD Billion)
- FIG 17. Asia Pacific market 2022 & 2032 (USD Billion)
- FIG 18. Latin America market 2022 & 2032 (USD Billion)
- FIG 19. Middle East & Africa market 2022 & 2032 (USD Billion)
- FIG 20. Global market, company market share analysis (2023)

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